



一级代理商：

深圳市弗瑞鑫电子有限公司

地址：深圳市宝安区西乡大道302号金源商务大厦B座三楼

frxelec



5. Abol e Ma im m Ra ing (Ta=25)

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7. O de Info ma ion

Pa N mbe

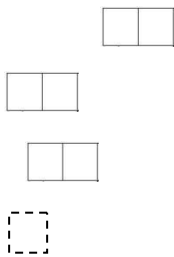
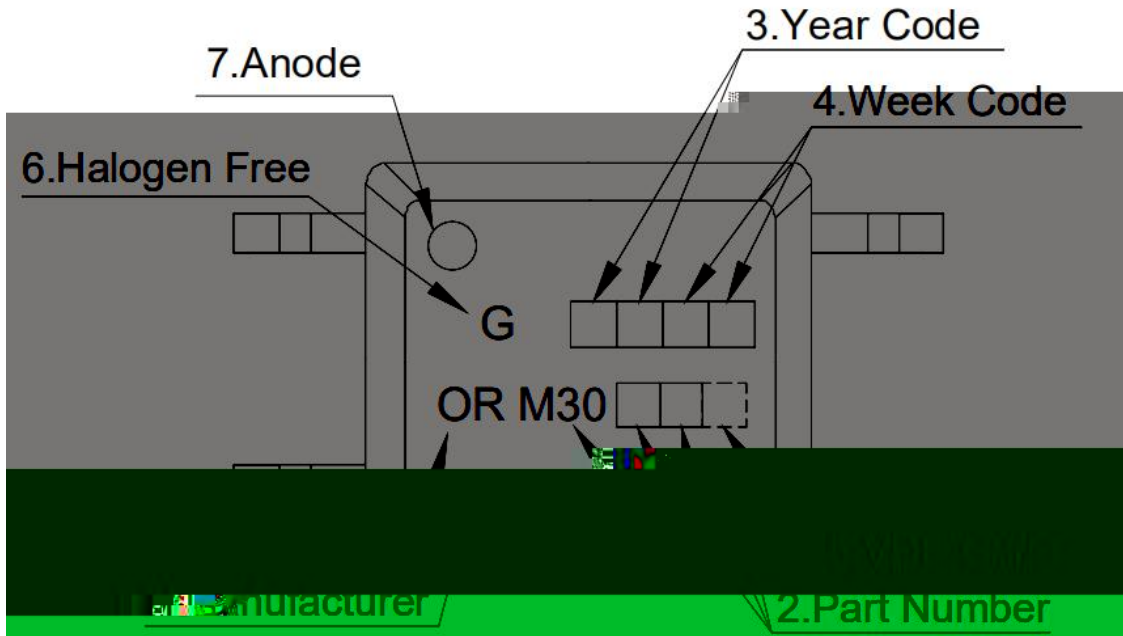
OR-M302X-W-Y-Z

o OR-M305X-W-Y-Z

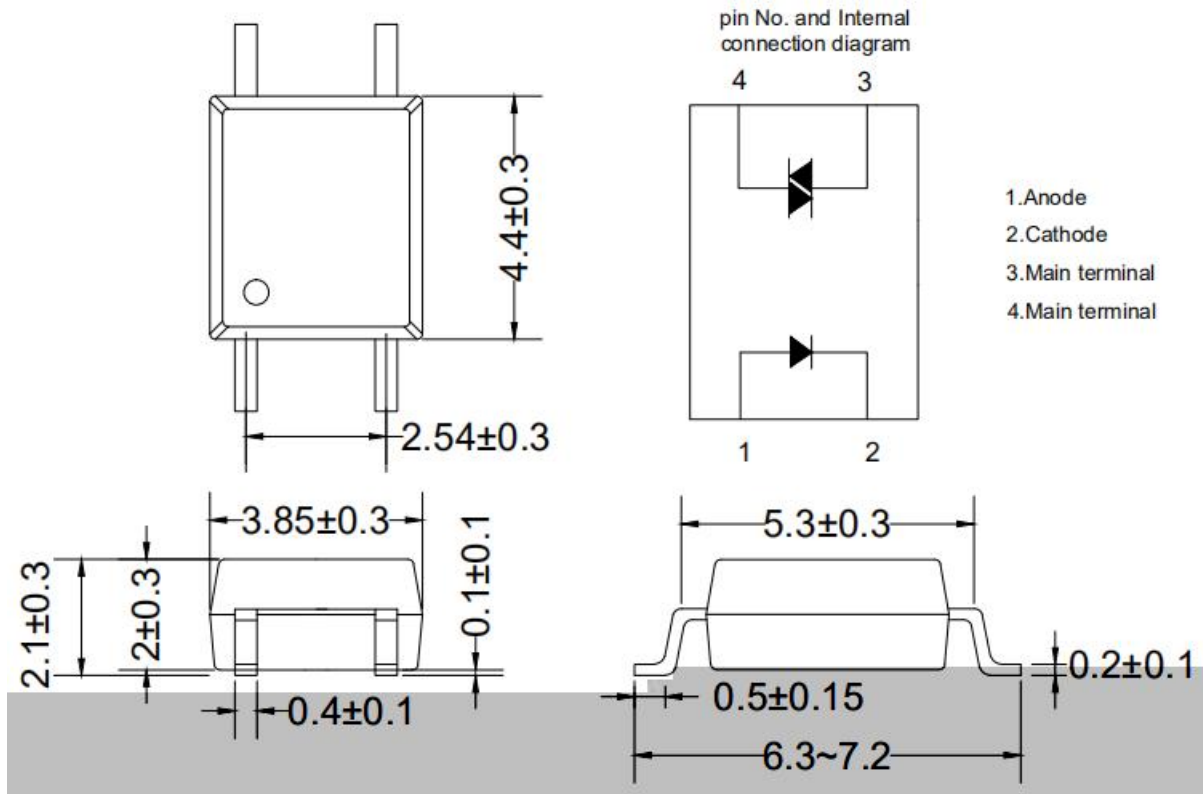
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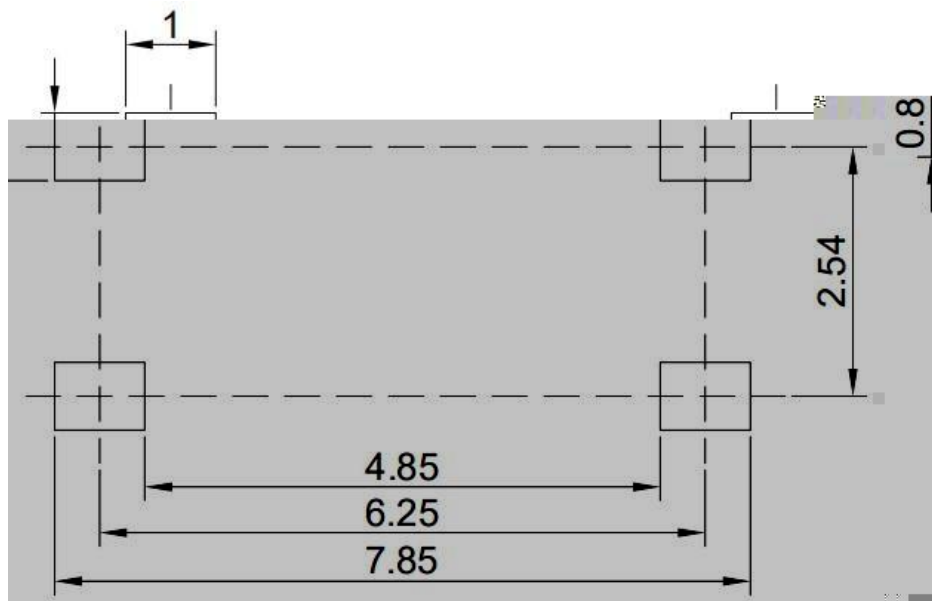
8. Naming Rule



9. Package Dimension

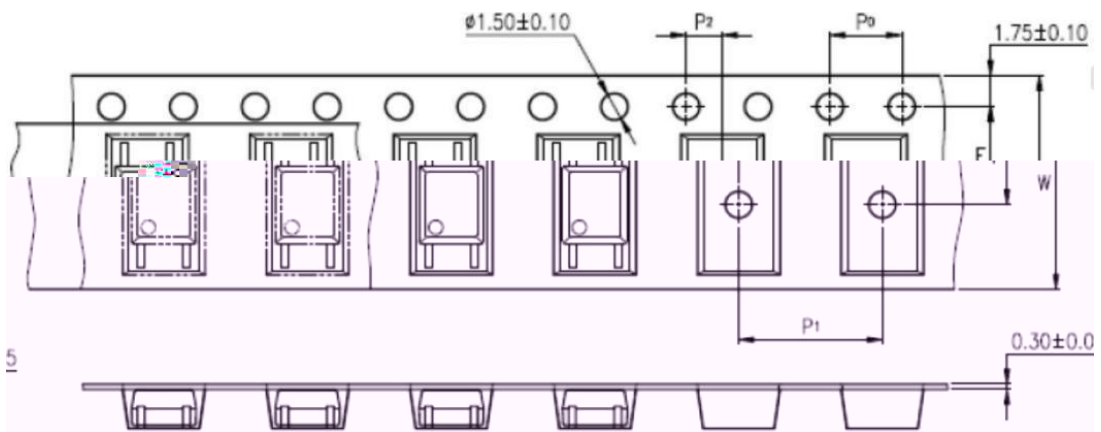
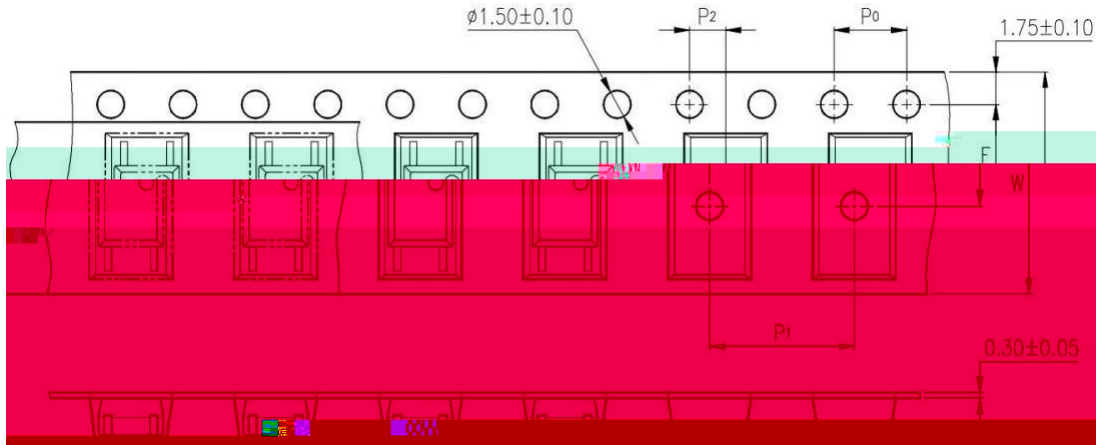


10. Recommended Foot Print Pattern (Mo n Pad)



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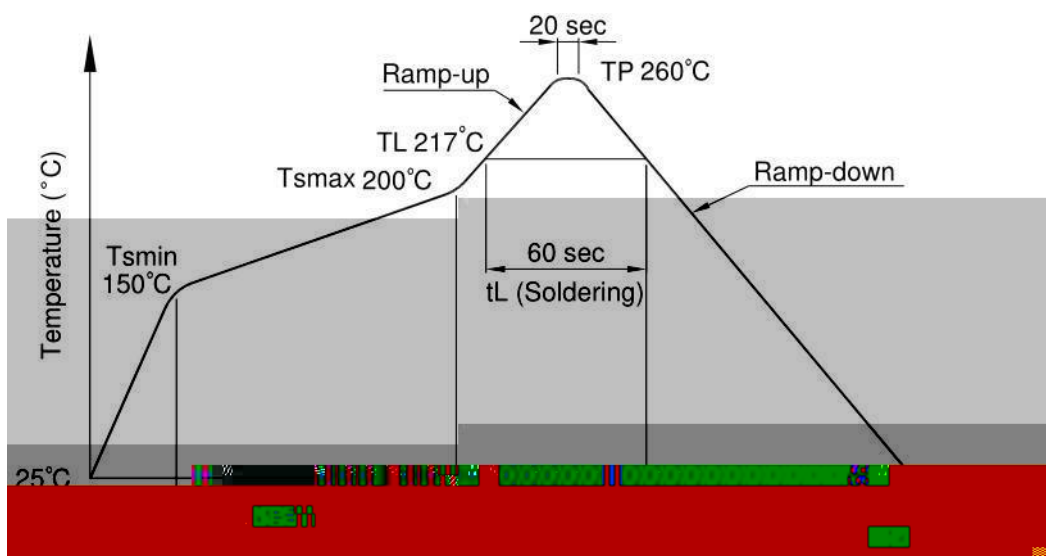
11. Ta ing Dimen ion





13. Temperature Profile Of Soldering

Profile Item	Condition





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14. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward current vs Ambient temperature

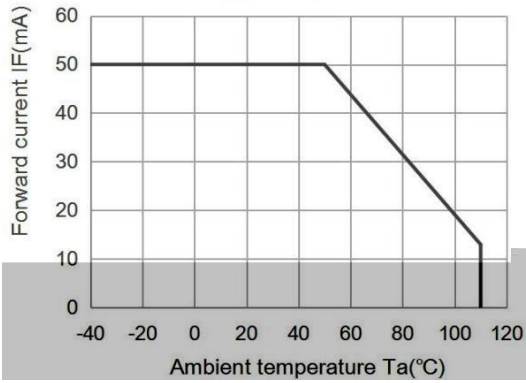


Fig.2 On-state current ITM (A) vs Ambient temperature

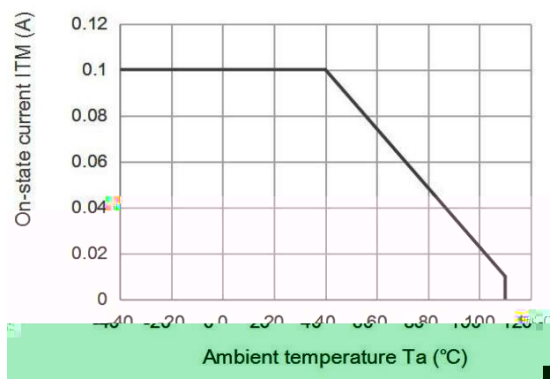


Fig.3 Minimum Trigger Current vs. Ambient temperature

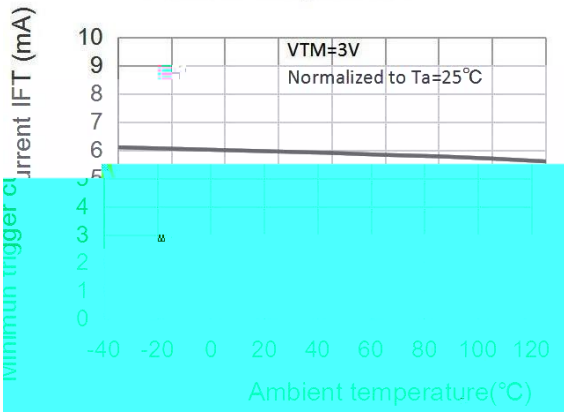


Fig.4 Forward current vs. Forward voltage

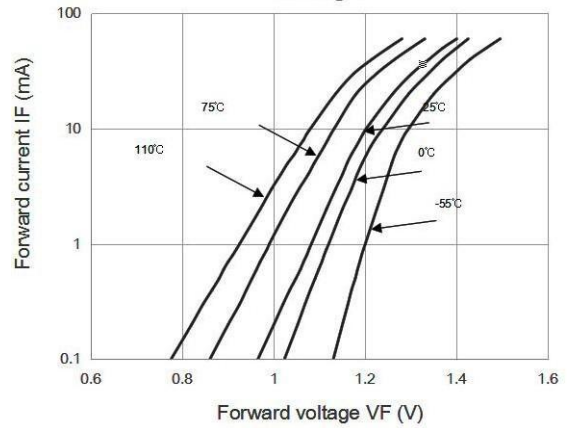


Fig.5 On-state voltage vs. Ambient temperature

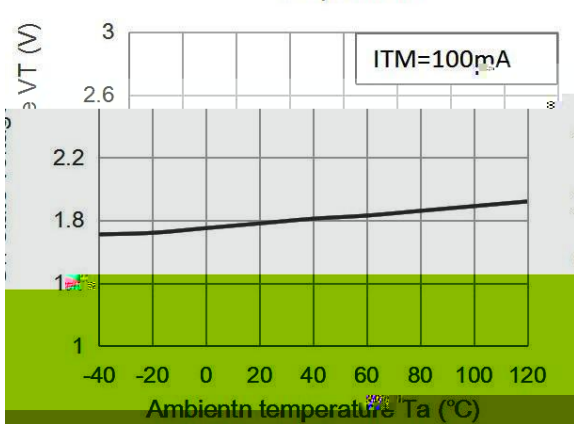


Fig.6 Holding current vs. Ambient temperature

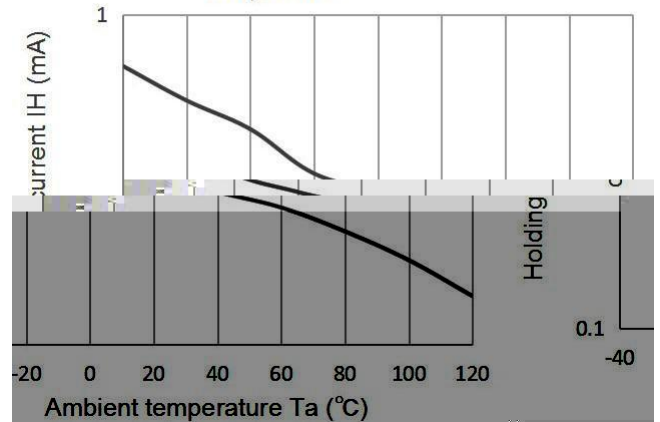


Fig.7 Repetitive peak off-state current vs. Temperature

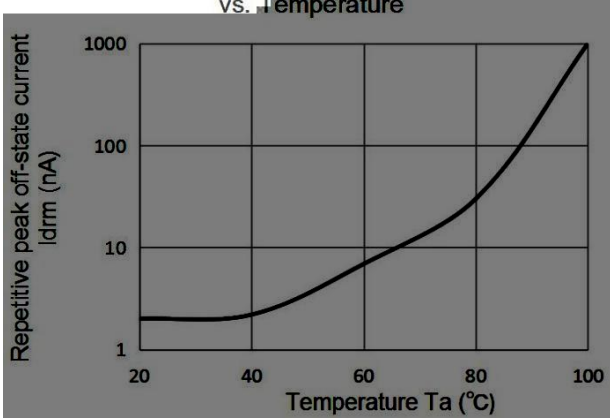
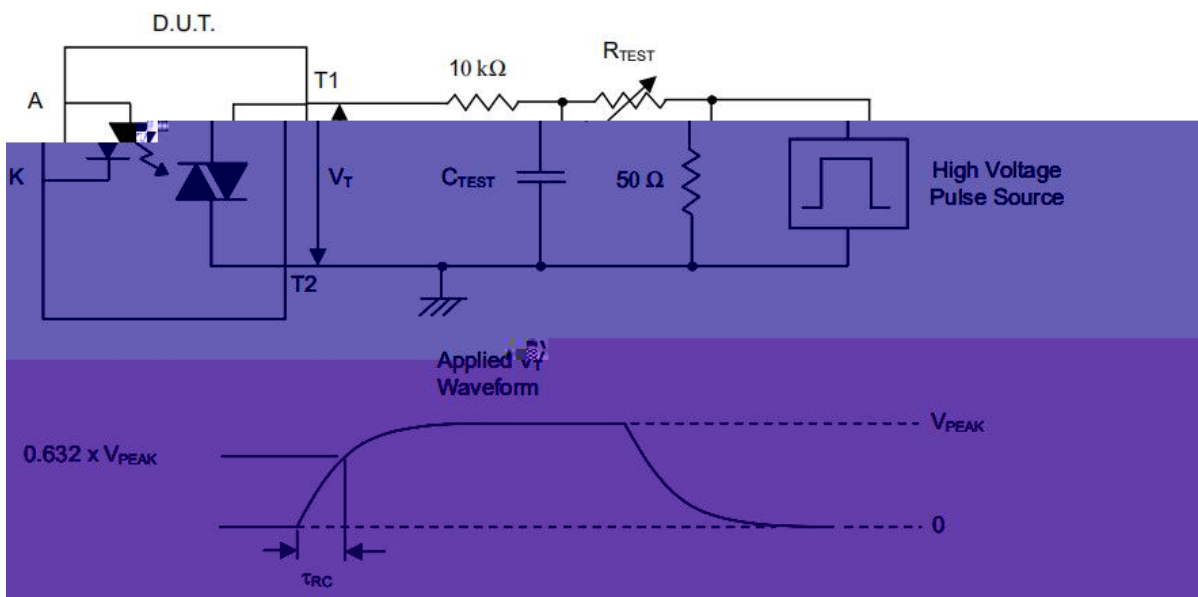
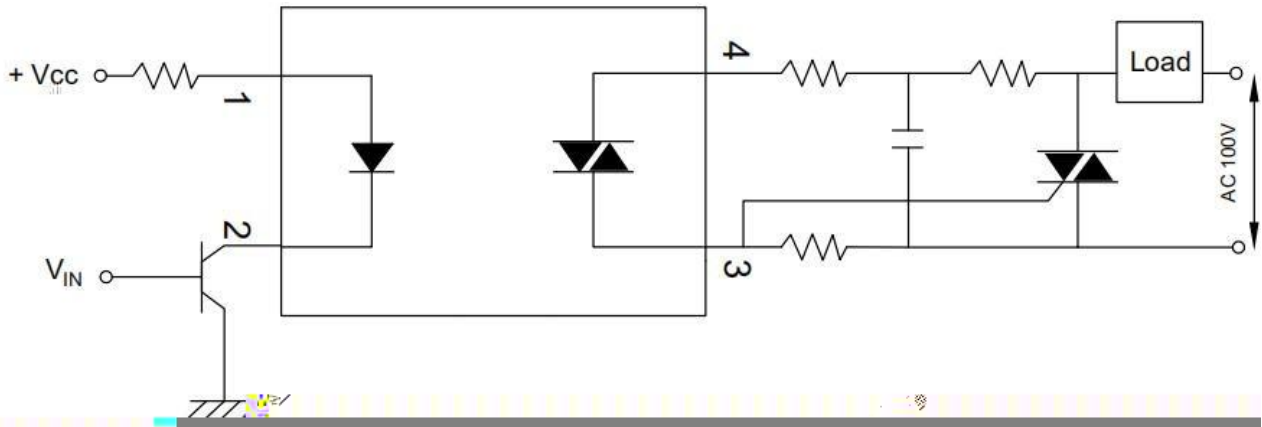
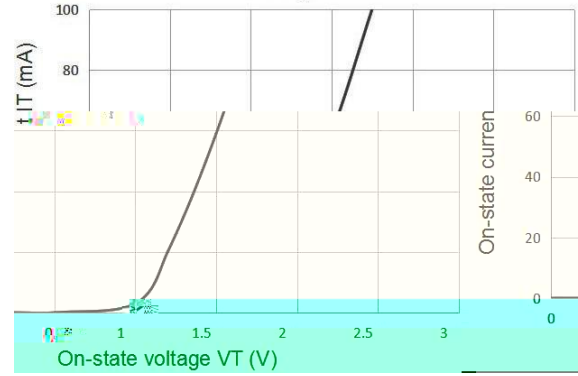


Fig.8 On-state current vs. On-state voltage



Measurement Method

